

型号：CFCL422113V-AS-S

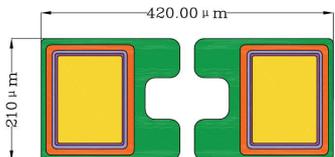
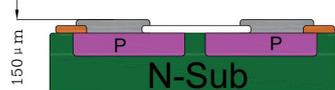
FEATURES

- ⊙ Low leakage current
- ⊙ Applicable to flip chip Zener package

Structure

- ⊙ Lateral PNP Bi-directional Structure
- ⊙ Structure: Dual pad

MECHANICAL DATA

 <p>Top view</p>	Die size($\mu\text{m} \times \mu\text{m}$) (without scribe line)		420.0*210.0
	Die thickness(μm)		140.0
Scribe line(μm)		40.0	
 <p>Cross section</p>	Bonding pad size(μm^2)	Top	150.0*120.0*2.0
	Top	Metallization	AuSn
		Thickness(μm)	3.0
	Bottom	Metallization	Si
Wafer size(mm)		$\phi 150$	
Quantity (K pcs)		159	

ABSOLUTE MAXIMUM RATINGS (TA=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating junction temperature	T_J	150	°C
Storage temperature range	T_{STG}	-55 to +150	°C
Power dissipation	P_d	100	mW

ELECTRICAL CHARACTERISTICS (TA=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward zener voltage	$V_{Z(F)}$	$I_F=10\text{mA}$	11	13	15	V
Reverse zener voltage	$V_{Z(R)}$	$I_Z=10\text{mA}$	11	13	15	V
Forward current	I_F	$V_F=9\text{V}$	-	-	0.1	μA
Reverse current	I_R	$V_R=9\text{V}$	-	-	0.1	μA

SCHEMATIC&PIN CONFIGURATION

